onsemi

MOSFET - Power, Single N-Channel, SUPERFET[®] V, Easy Drive, TO247-3L 600 V, 99 mΩ, 33 A

NTHL099N60S5

Description

SUPERFET V MOSFET Easy Drive series combines excellent switching performance without sacrificing ease of use and EMI issues for both hard and soft switching topologies.

Features

- $650 \text{ V} @ \text{T}_{\text{J}} = 150^{\circ}\text{C}$
- Typ. R_{DS(on)} = 79.2 mΩ
- 100% Avalanche Tested
- Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Telecom / Server Power Supplies
- EV Charger / UPS / Solar / Industrial Power Supplies

ABSOLUTE MAXIMUM RATINGS (T_J = 25° C, Unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain-to-Source Voltage	V _{DSS}	600	V	
Gate-to-Source Voltage	Gate-to-Source Voltage DC		±30	V
	AC (f > 1 Hz)		±30	
Continuous Drain Current	Continuous Drain Current $T_{C} = 25^{\circ}C$		33*	А
	$T_{C} = 100^{\circ}C$		20*	
Power Dissipation	Power Dissipation $T_{C} = 25^{\circ}C$		184	W
Pulsed Drain Current (Note 1)	Pulsed Drain Current (Note 1) $T_C = 25^{\circ}C$		95*	А
Pulsed Source Current (Body Diode) (Note 1) $T_C = 25^{\circ}C$		I _{SM}	95*	A
Operating Junction and Storage Range	T _J , T _{STG}	–55 to +150	°C	
Source Current (Body Diode)		I _S	33*	А
		E _{AS}	232	mJ
Avalanche Current	I _{AS}	5.1	А	
Repetitive Avalanche Energy (N	E _{AR}	1.84	mJ	
MOSFET dv/dt	dv/dt	120	V/ns	
Peak Diode Recovery dv/dt (No		50		
Lead Temperature for Soldering (1/8" from case for 10 seconds)	ΤL	260	°C	

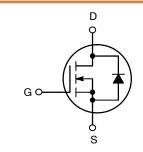
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. *Drain current limited by maximum junction temperature.

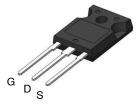
1. Repetitive rating: pulse-width limited by maximum junction temperature.

2. $I_{SD} \le 13.5$ A, di/dt ≤ 200 A/µs, $V_{DD} \le 400$ V, starting $T_J = 25^{\circ}$ C.

©	Semiconductor Components Industries, LLC, 2021	nents Industries, LLC, 2021	
Α	gust, 2021 – Rev. 2	v. 2	

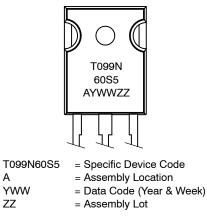
V _{DSS} R _{DS(ON)} MAX		I _D MAX
600 V	99 mΩ @ 10 V	33 A





TO-247 Long Leads CASE 340CX

MARKING DIAGRAM



ORDERING INFORMATION

Device	Package	Shipping
NTHL099N60S5	TO-247	30 Units / Tube

1

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case, Max.	$R_{ ext{ heta}JC}$	0.68	°C/W
Thermal Resistance, Junction-to-Ambient, Max.	$R_{ hetaJA}$	40	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS		•			•	4
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I _D = 1 mA, T _J = 25°C	600	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$\Delta V_{(BR)DSS}/ \Delta T_J$	I_D = 10 mA, Referenced to 25°C	_	630	-	mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V_{GS} = 0 V, V_{DS} = 600 V, T_J = 25 $^\circ C$	_	-	1	μΑ
Gate-to-Source Leakage Current	I _{GSS}	V_{GS} = ±30 V, V_{DS} = 0 V	_	-	±100	nA
ON CHARACTERISTICS	•	•				
Drain-to-Source On Resistance	R _{DS(on)}	V_{GS} = 10 V, I_D = 13.5 A, T_J = 25 $^\circ C$	_	79.2	99	mΩ
Gate Threshold Voltage	V _{GS(th)}	V_{GS} = V_{DS} , I_D = 2.8 mA, T_J = 25°C	2.4	-	4.0	V
Forward Trans-conductance	9fs	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 13.5 \text{ A}$	-	26	-	S
CHARGES, CAPACITANCES & GATE	RESISTANCE	•			•	
Input Capacitance	C _{ISS}	V_{DS} = 400 V, V_{GS} = 0 V, f = 250 kHz	-	2500	-	pF
Output Capacitance	C _{OSS}			41	-	1
Time Related Output Capacitance	C _{OSS(tr.)}			642	-	
Energy Related Output Capacitance	C _{OSS(er.)}	V_{DS} = 0 V to 400 V, V_{GS} = 0 V	_	70	-	
Total Gate Charge	Q _{G(tot)}	V_{DD} = 400 V, I _D = 13.5 A, V _{GS} = 10 V	_	48	-	nC
Gate-to-Source Charge	Q _{GS}		_	12	-	
Gate-to-Drain Charge	Q _{GD}		_	14	-	
Gate Resistance	R _G	f = 1 MHz	-	6.9	-	Ω
SWITCHING CHARACTERISTICS		•				
Turn-On Delay Time	t _{d(on)}	$V_{GS} = 0/10 \text{ V}, V_{DD} = 400 \text{ V},$	-	26	-	ns
Rise Time	t _r	l _D = 13.5 A, R _G = 4.7 Ω	-	17	-	
Turn-Off Delay Time	t _{d(off)}	1	-	92	-	
Fall Time	t _f	1	-	4.2	-	
SOURCE-TO-DRAIN DIODE CHARAC	TERISTICS			•	•	•
Forward Diode Voltage	V _{SD}	V_{GS} = 0 V, I_{SD} = 13.5 A, T_{J} = 25°C	-	-	1.2	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

t_{RR}

 Q_{RR}

 $\begin{array}{l} V_{GS} = 0 \,\, V, \, I_{SD} = 13.5 \,\, A, \\ dI/dt = 100 \,\, A/\mu s, \, V_{DD} = 400 \,\, V \end{array}$

310

4627

_

ns

nC

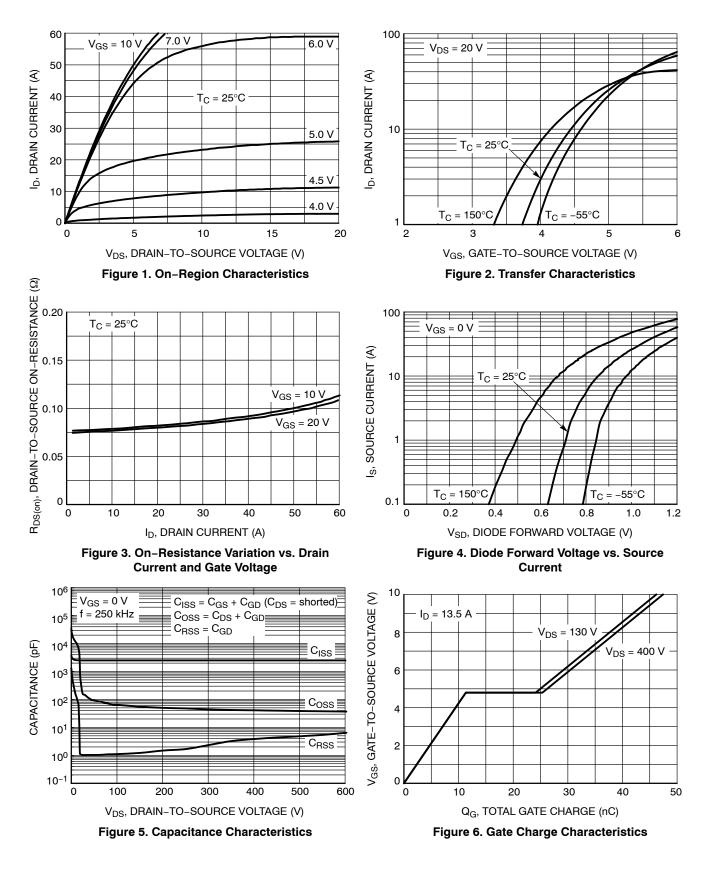
_

_

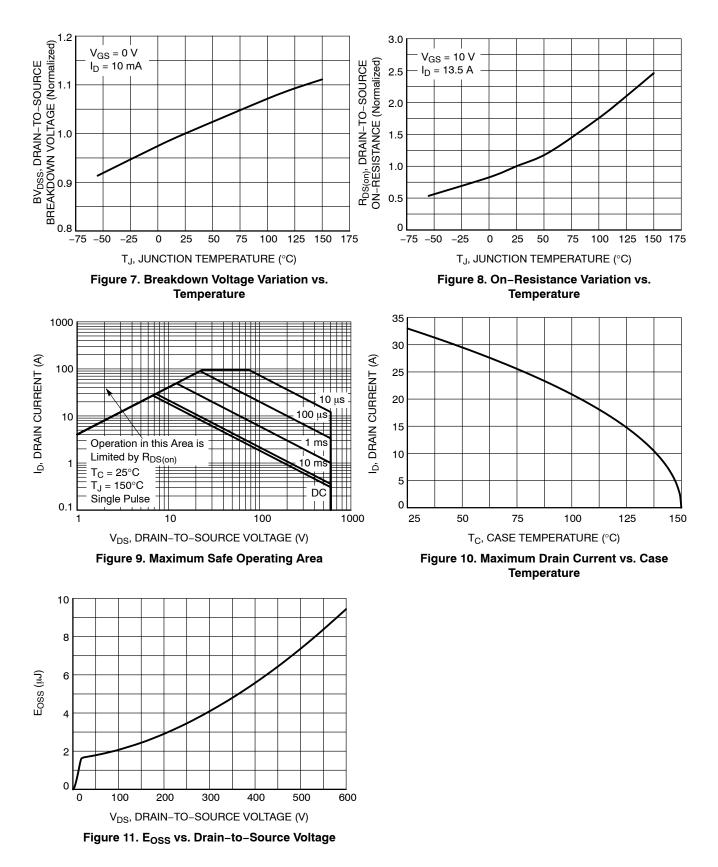
Reverse Recovery Time

Reverse Recovery Charge

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

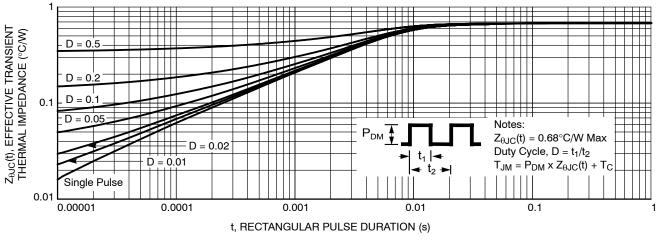


Figure 12. Transient Thermal Impedance

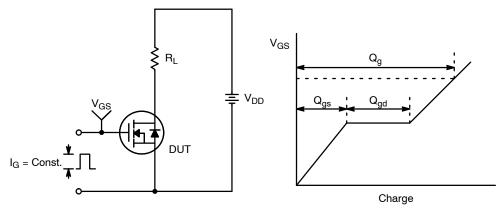


Figure 13. Gate Charge Test Circuit & Waveform

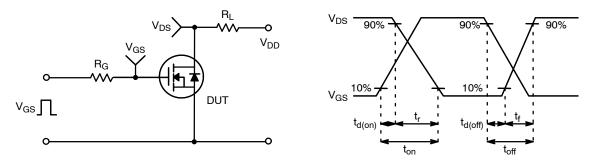


Figure 14. Resistive Switching Test Circuit & Waveforms

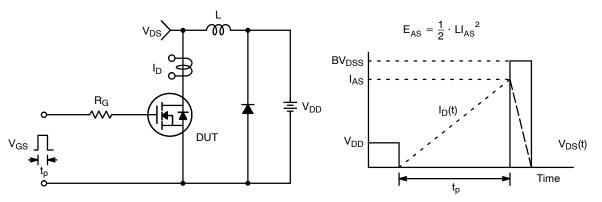


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

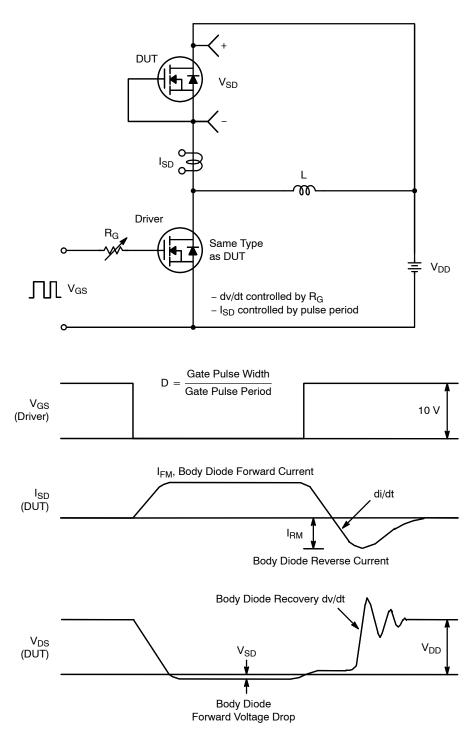
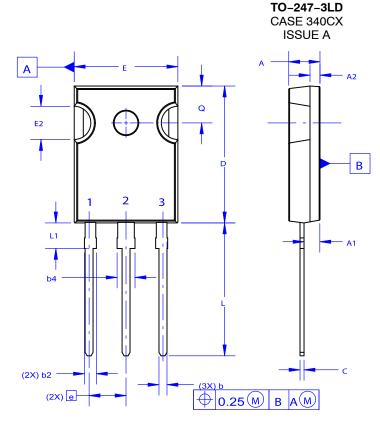


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

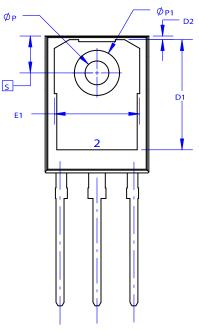
SUPERFET is a registered trademark of Semiconductor Components Industries, LLC or its subsidiaries in the United States and/or other countries.

PACKAGE DIMENSIONS



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
 D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØР	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
ØP1	6.60	6.80	7.00		

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and calcular performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

TECHNICAL SUPPORT

onsemi Website: www.onsemi.com

Email Requests to: orderlit@onsemi.com

North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support: Phone: 00421 33 790 2910 For additional information, please contact your local Sales Representative

٥